

Abstract

Disclosed is a method for forming a conductor on a dielectric. The method commences with the deposition of a conductive thickfilm on the dielectric, followed by a "subsintering" of the conductive thickfilm. Either
5 before or after the subsintering, the conductive thickfilm is patterned to define at least one conductor. After subsintering, the conductive thickfilm is etched to expose the conductor(s), and the conductor(s) are then fired. A brief chemical etch may be used after the final firing step if improved wire-bondability is required.